

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Che Hsieh</td> <td>01/28/2011</td> </tr> <tr> <td>John H. Lau</td> <td>01/28/2011</td> </tr> <tr> <td>Ra-Min Tain</td> <td>01/28/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Che Hsieh	01/28/2011	John H. Lau	01/28/2011	Ra-Min Tain	01/28/2011
Name	Execution Date								
Ming-Che Hsieh	01/28/2011								
John H. Lau	01/28/2011								
Ra-Min Tain	01/28/2011								
RECEIVING PARTY DATA									
Name:	Industrial Technology Research Institute								
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City:	Hsinchu								
State/Country:	TAIWAN								
Postal Code:	31040								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13023545</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13023545				
Property Type	Number								
Application Number:	13023545								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	Belinda Lee								

Total Attachments: 2
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PATENT
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ASSIGNMENT

WHEREAS,

1. Ming-Che Hsieh
2. John H. Lau
3. Ra-Min Tain

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **FABRICATING METHOD AND TESTING METHOD OF SEMICONDUCTOR DEVICE AND MECHANICAL INTEGRITY TESTING APPARATUS**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ming-Che Hsieh
Sole or First Joint Inventor: Ming-Che Hsieh

Date: 2011/01/28

Signature: John H. Lau
Second Joint Inventor (if any): John H. Lau

Date: 1/28/2011

Signature: Ra-Min Tain
Third Joint Inventor (if any): Ra-Min Tain

Date: 2011/01/28